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REVISIONS			
REV	DESCRIPTION	DATE	BY
A	ECO 2104138 INITIAL RELEASE	01/20/2010	J. HOLM
B	ECO 2121955 CORRECT APERTURE X DIMENSIONS VIEW D	1/23/2012	BMH
C	ECO 2144971 ADD (FQD PACKAGE) TO TITLE	9/11/2014	MAA

- NOTES UNLESS OTHERWISE SPECIFIED:
- 1 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY.
 - 2 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM ALLOWED VALUE OF 0.6 DEGREES.
 - 3 BOUNDARY MIRRORS SURROUNDING THE DMD ACTIVE ARRAY.
 - 4 DMD MARKING TO APPEAR ON SYMBOLIZATION PAD.
 - 5 NOTCH DIMENSIONS ARE DEFINED BY UPPERMOST LAYERS OF CERAMIC, AS SHOWN IN SECTION A-A.
 - 6 ENCAPSULANT TO BE CONTAINED WITHIN DIMENSIONS SHOWN IN VIEWS C AND D (SHEET 2).
 - 7 WHILE ONLY THE THREE DATUM A TARGET AREAS A1, A2, AND A3 ARE USED FOR MEASUREMENT, ALL 4 CORNERS SHOULD BE CONTACTED, INCLUDING E1, WHEN MOUNTING IN SYSTEM.

D

C

B

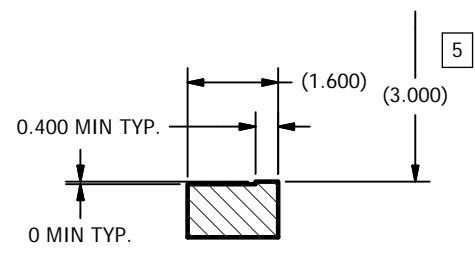
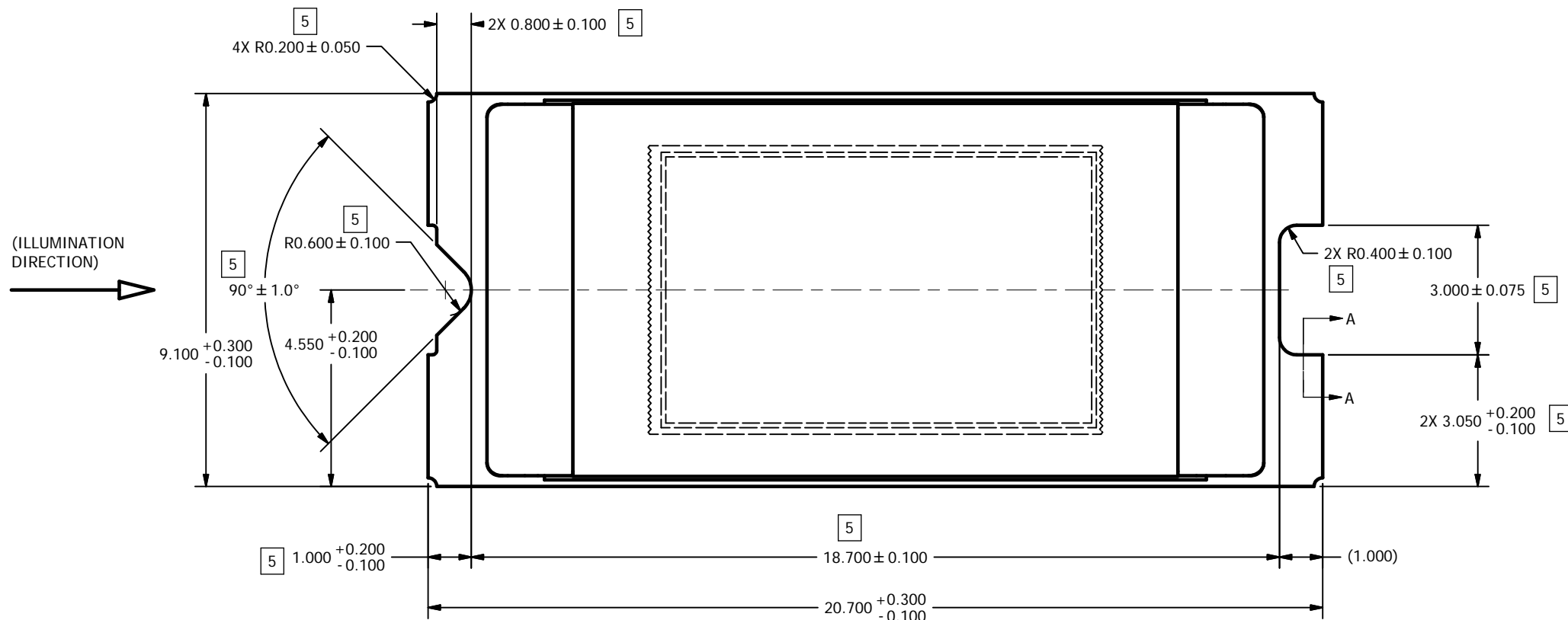
A

D

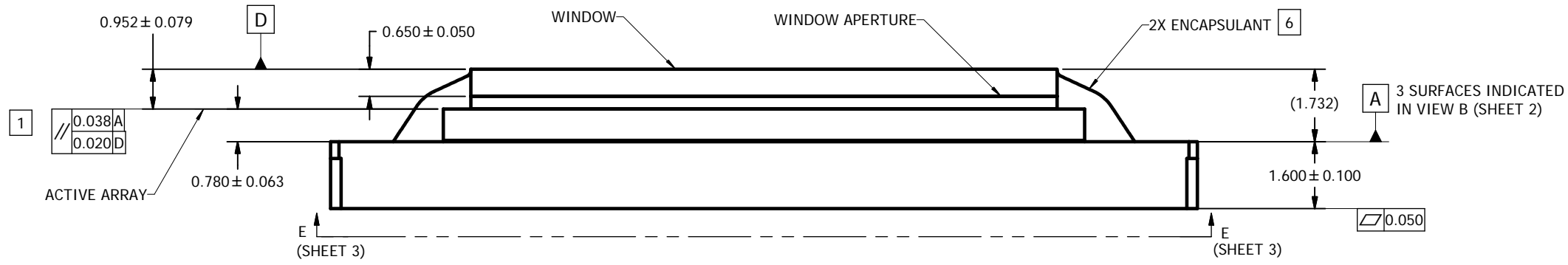
C

B

A



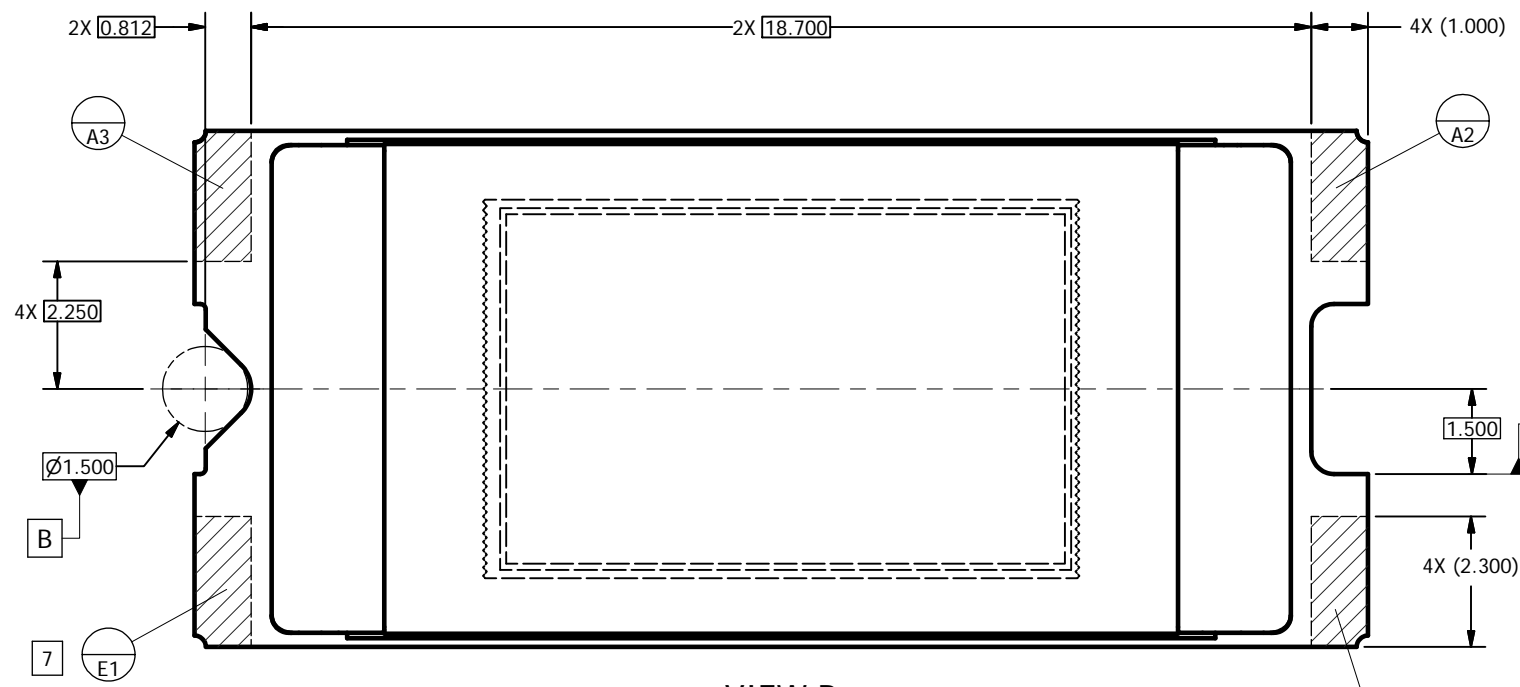
SECTION A-A
NOTCH OFFSETS



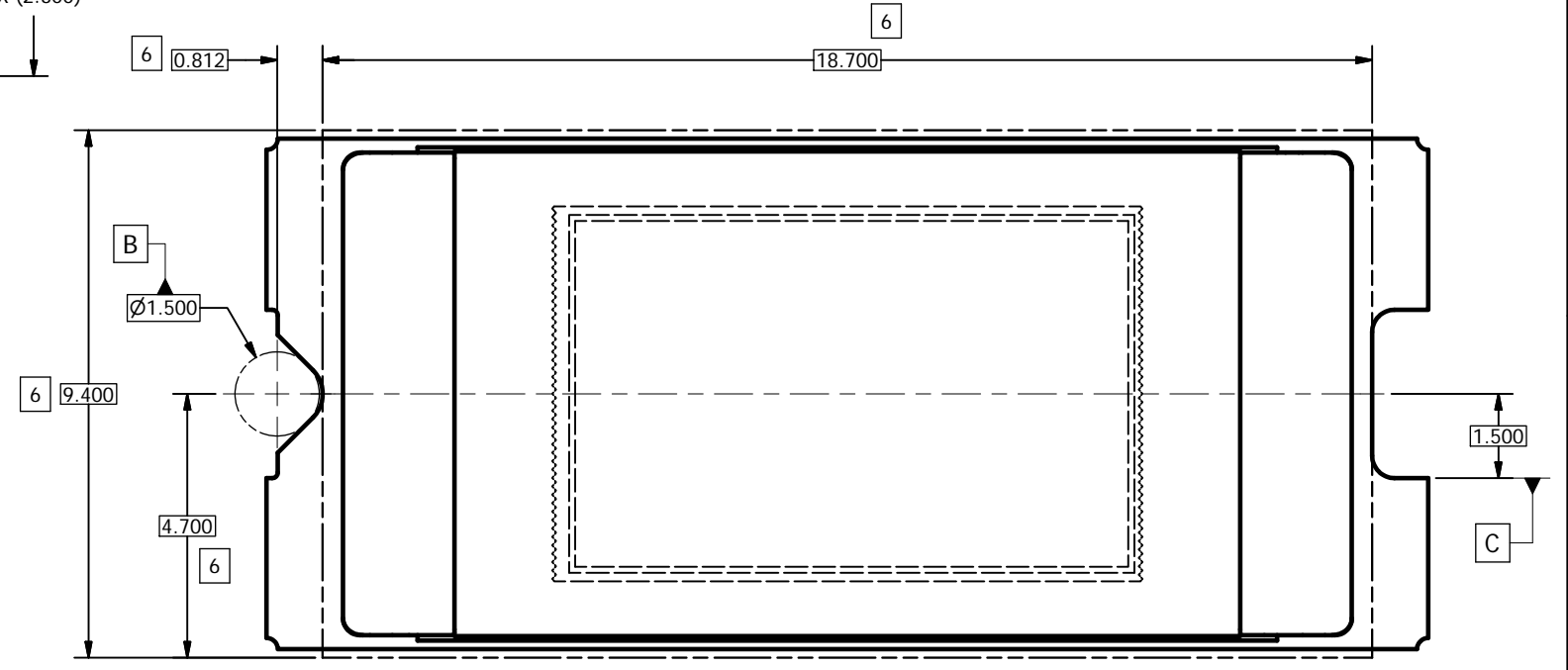
UNLESS OTHERWISE SPECIFIED	
● DIMENSIONS ARE IN MILLIMETERS	
● TOLERANCES:	
ANGLES ± 1°	
2 PLACE DECIMALS ± 0.25	
1 PLACE DECIMALS ± 0.50	
● DIMENSIONAL LIMITS APPLY BEFORE PROCESSES	
● INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994	
● REMOVE ALL BURRS AND SHARP EDGES	
● PARENTHETICAL INFORMATION FOR REFERENCE ONLY	

DRAWN	DATE
J. HOLM	12/11/2009
ENGINEER	
J. HOLM	12/11/2009
QA/CE	
P. KONRAD	1/20/2010
CM	
F. ARMSTRONG	1/20/2010
J. HALL	1/20/2010
APPROVED	

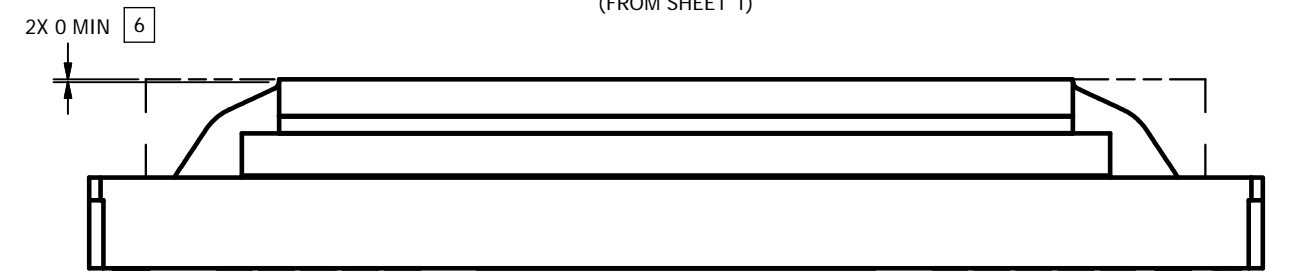
 TEXAS INSTRUMENTS <small>Dallas, Texas</small>	
TITLE ICD, MECHANICAL, DMD, .45 WXGA-800 DDR SERIES 310 (FQD PACKAGE)	
SIZE D	DWG NO. 2510852
SCALE 15:1	REV C
SHEET 1 OF 3	



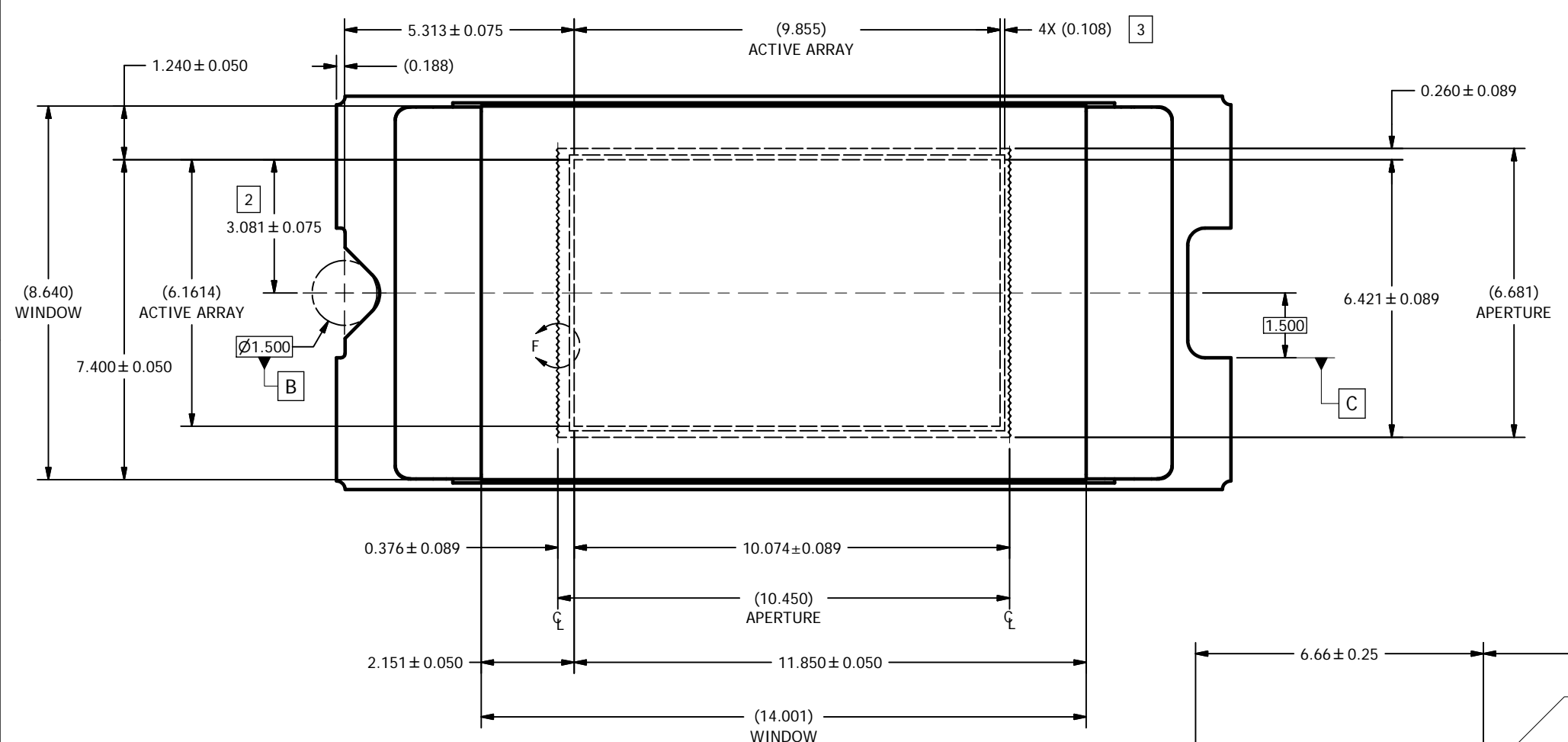
VIEW B
DATUMS A, B, C, AND E
SCALE 15 : 1
(FROM SHEET 1)



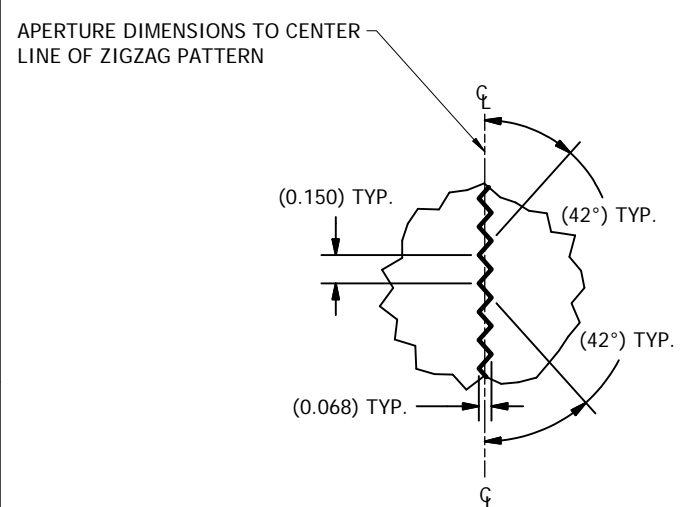
VIEW C
ENCAPSULANT MAXIMUM X/Y DIMENSIONS
SCALE 15 : 1
(FROM SHEET 1)



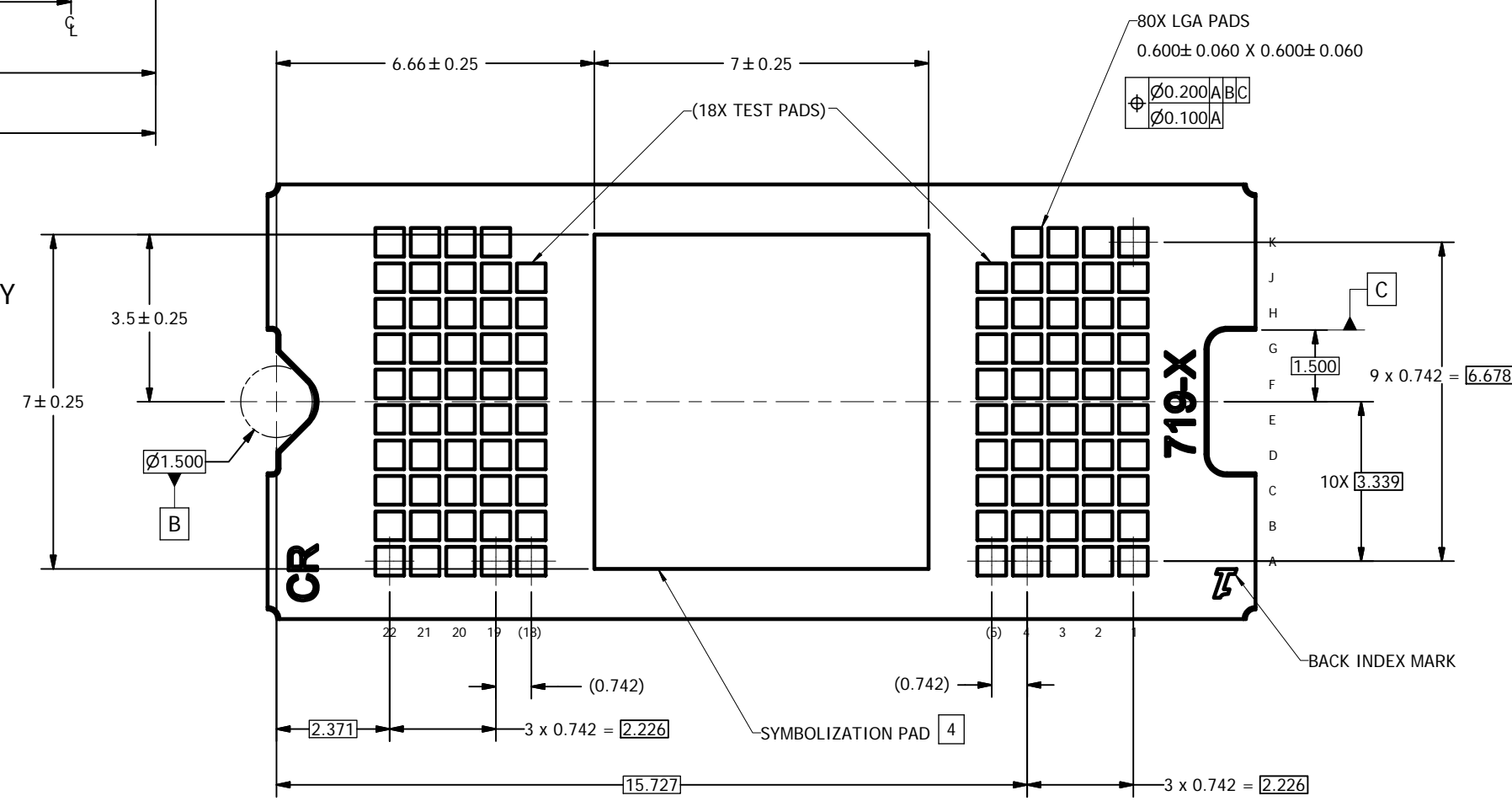
VIEW D
ENCAPSULANT MAXIMUM HEIGHT
SCALE 15 : 1



VIEW D
WINDOW AND ACTIVE ARRAY
(FROM SHEET 1)



DETAIL F
APERTURE SHORT EDGES
SCALE 50 : 1



VIEW E-E
BACK SIDE METALLIZATION
(FROM SHEET 1)

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